Final Product Change Notification 202002004F01

Issue Date: 12-Mar-2020
Effective Date: 10-Jun-2020

Dear *PCN NXP*,

Please find below a Quality Notification that has been distributed by NXP.

Change Category

- [ ] Wafer Fab Process
- [ ] Wafer Fab Materials
- [ ] Wafer Fab Location
- [ ] Firmware
- [X] Assembly Process
- [ ] Assembly Materials
- [ ] Assembly Location
- [ ] Other
- [ ] Product Marking
- [ ] Mechanical Specification
- [ ] Packing/Shipping/Labeling
- [ ] Test Location
- [ ]Test Process
- [ ] Test Equipment
- [ ] Design
- [ ] Errata
- [ ] Electrical spec./Test coverage

SAC57D54H/53M/52L Die Thickness Increase to 280um For The 516MAPBGA 27*27

Description of Change

NXP Semiconductors announces a change in die thickness for the SAC57D54H/ 53M/ 52L, Mask Set N87P from the current 179um to 280um.

The above change coincides with DeQuMa ID: SEM-PW-03.

Reason for Change

Die thickness increase is to improve product quality, reliability and C55 product family standardization.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request
Samples part number made available is KAC57D54HCVMOR.

Production

Planned first shipment 11-Jun-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file
Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 11-Apr-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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